



SOT2086-1

HVQFN116, thermal enhanced very thin quad flat package, no leads, 116 terminals, 0.5 mm pitch, 9 mm x 9 mm x 0.85 mm body

10 June 2022

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN116
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	03-04-2022
Manufacturer package code	98ASA01710D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	9	-	mm
package width	-	9	-	mm
seated height	-	0.85	9	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	116	-	



HVQFN116, thermal enhanced very thin quad flat package, no leads, 116 terminals, 0.5 mm pitch, 9 mm x 9 mm x 0.85 mm body

2 Package outline

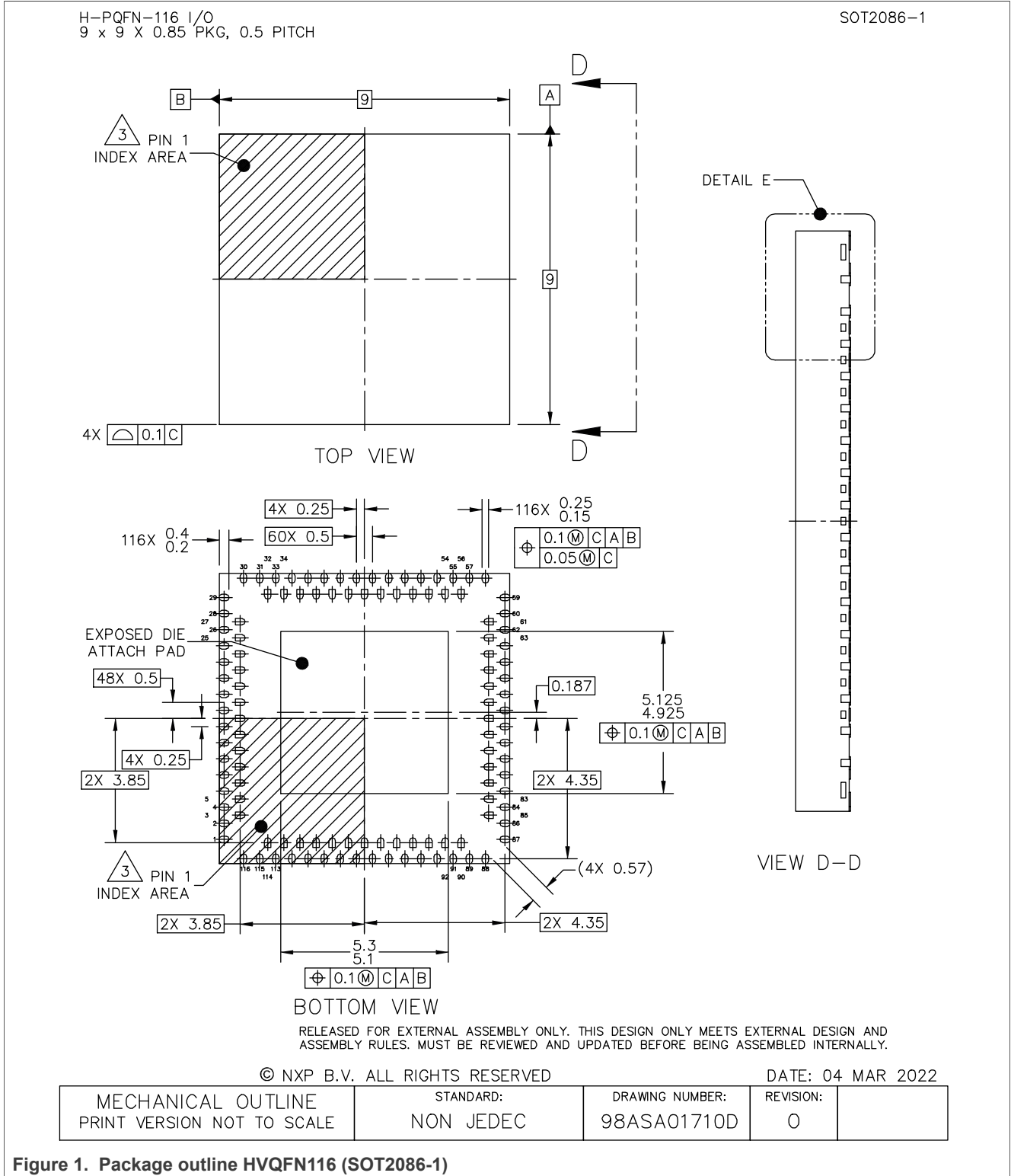


Figure 1. Package outline HVQFN116 (SOT2086-1)

HVQFN116, thermal enhanced very thin quad flat package, no leads, 116 terminals, 0.5 mm pitch, 9 mm x 9 mm body
9 mm x 0.85 mm body

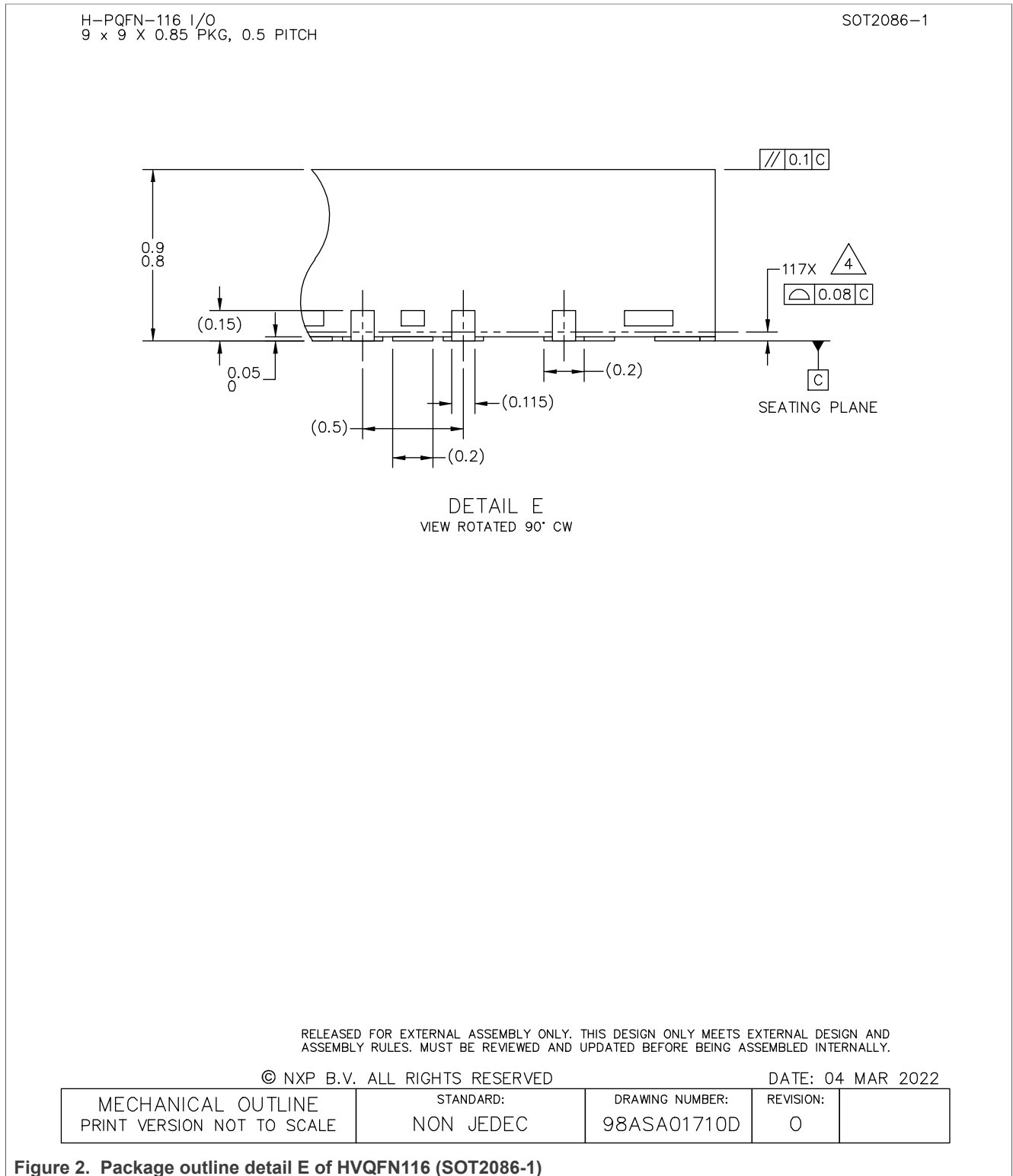
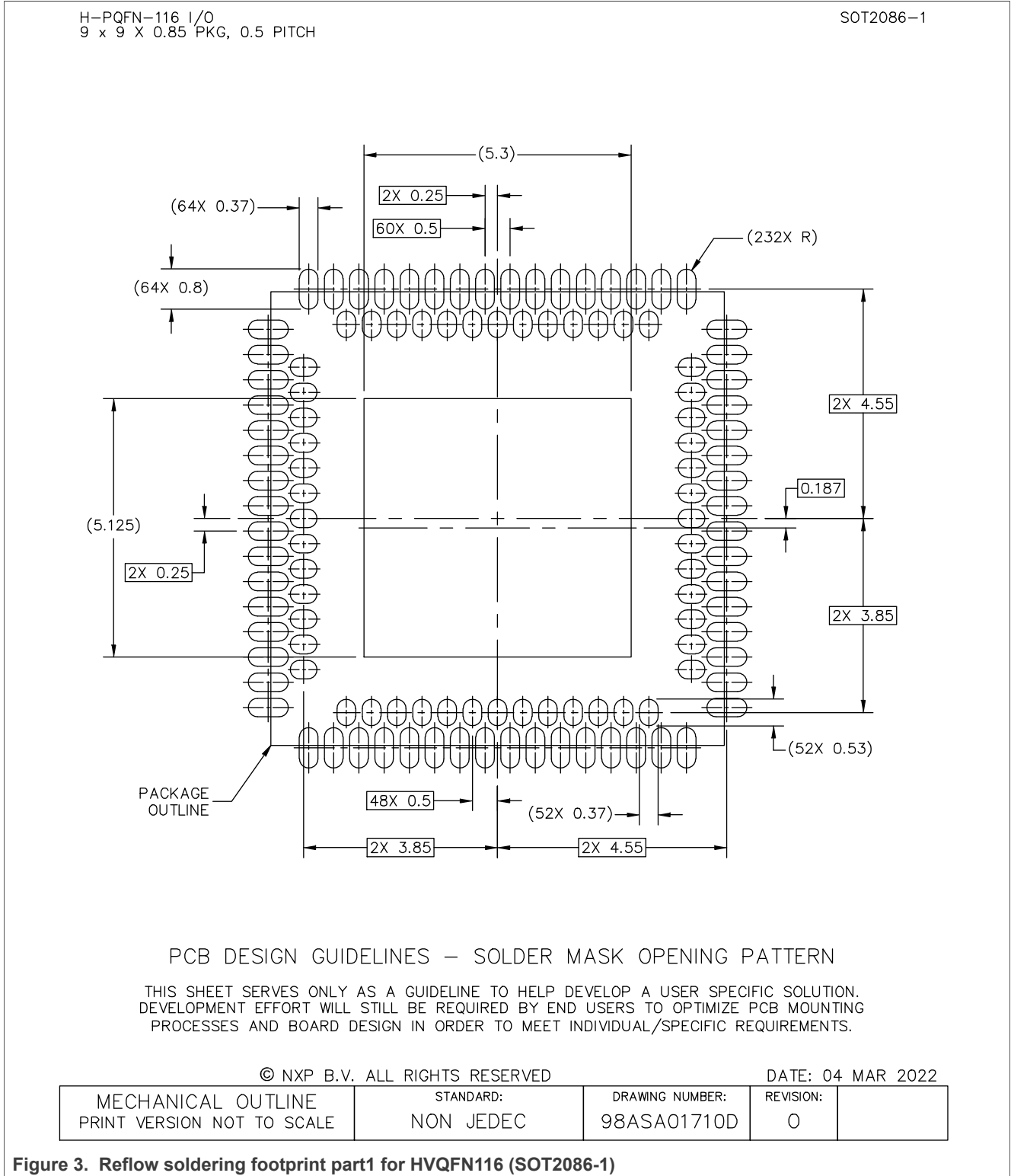
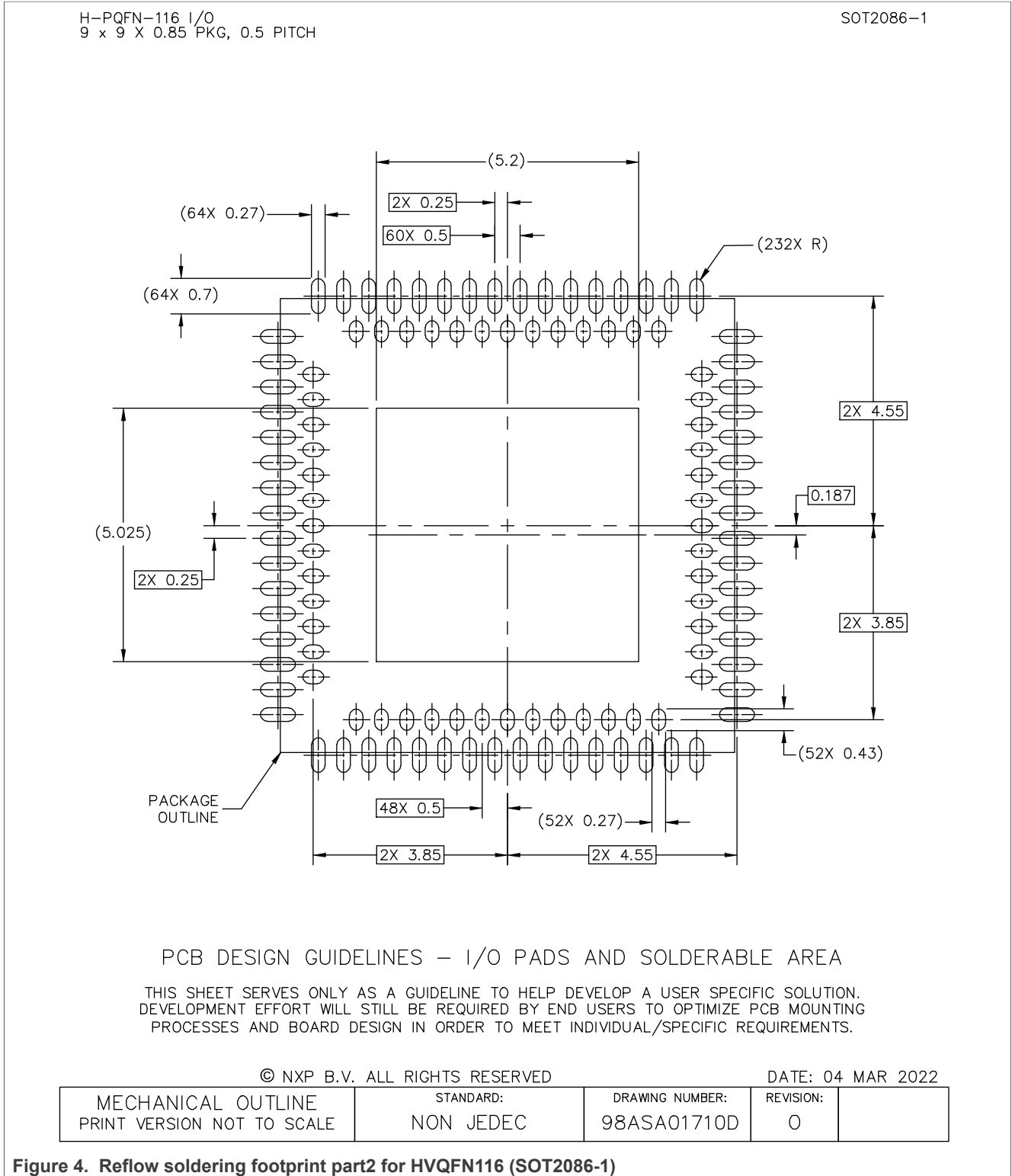


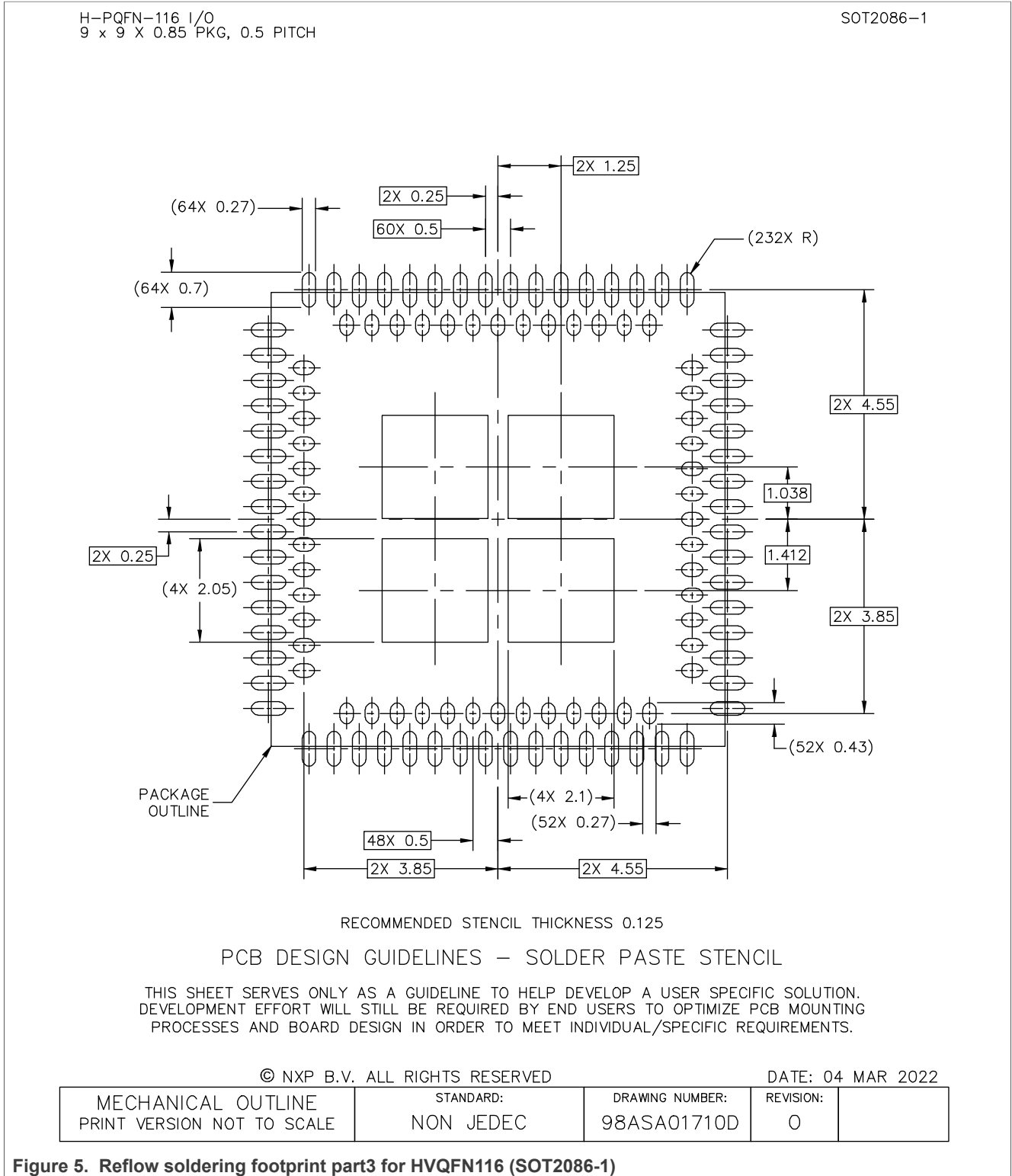
Figure 2. Package outline detail E of HVQFN116 (SOT2086-1)

3 Soldering



HVQFN116, thermal enhanced very thin quad flat package, no leads, 116 terminals, 0.5 mm pitch, 9 mm x 9 mm x 0.85 mm body





HVQFN116, thermal enhanced very thin quad flat package, no leads, 116 terminals, 0.5 mm pitch, 9 mm x 9 mm x 0.85 mm body

H-PQFN-116 I/O
9 x 9 X 0.85 PKG, 0.5 PITCH

SOT2086-1

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.
5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.

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DATE: 04 MAR 2022

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01710D	REVISION: 0	
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Figure 6. Package outline note HVQFN116 (SOT2086-1)

4 Legal information

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